

## N-Ch 40V Fast Switching MOSFETs

- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

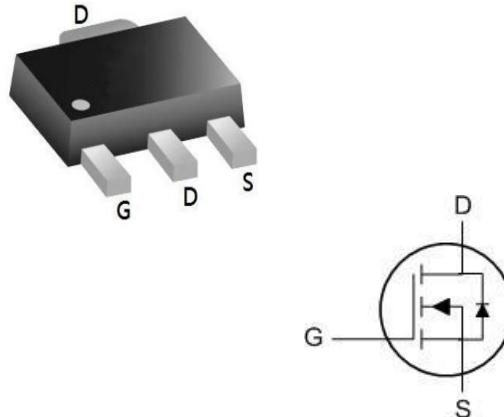
## Product Summary



BVDSS	RDS(ON)	ID
40V	19mΩ	8A

## Description

## SOT89-3L Pin Configuration



The XR8N04Q is the high cell density trenched P-ch MOSFETs, which provides excellent RDS(ON) and efficiency for most of the small power switching and load switch applications.

The XR8N04Q meet the RoHS and Green Product requirement with full function reliability approved.

Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter		Max.	Units
$V_{DSS}$	Drain-Source Voltage		40	V
$V_{GSS}$	Gate-Source Voltage		$\pm 20$	V
$I_D$	Continuous Drain Current	$T_A = 25^\circ\text{C}$	8.0	A
		$T_A = 100^\circ\text{C}$	4	A
$I_{DM}$	Pulsed Drain Current <sup>note1</sup>		32.8	A
EAS	Single Pulsed Avalanche Energy <sup>note2</sup>		13	mJ
$P_D$	Power Dissipation	$T_A = 25^\circ\text{C}$	2.0	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient		73	$^\circ\text{C}/\text{W}$
$T_J, T_{STG}$	Operating and Storage Temperature Range		-55 to +150	$^\circ\text{C}$

## N-Ch 40V Fast Switching MOSFETs

N-Channel Electrical Characteristics ( $T_J=25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristics</b>						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=250\mu\text{A}$	40	-	-	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{DS}=40\text{V}$ , $V_{GS}=0\text{V}$	-	-	1.0	$\mu\text{A}$
$I_{GSS}$	Gate to Body Leakage Current	$V_{DS}=0\text{V}$ , $V_{GS}=\pm 20\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$ , $I_D=250\mu\text{A}$	1.0	1.5	2.5	V
$R_{DS(\text{on})}$ note3	Static Drain-Source on-Resistance	$V_{GS}=10\text{V}$ , $I_D=8\text{A}$	-	19	24	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$ , $I_D=5\text{A}$	-	25	35	$\text{m}\Omega$
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS}=20\text{V}$ , $V_{GS}=0\text{V}$ , $f=1.0\text{MHz}$	-	633	-	pF
$C_{oss}$	Output Capacitance		-	67	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	58	-	pF
$Q_g$	Total Gate Charge		-	12	-	nC
$Q_{gs}$	Gate-Source Charge	$V_{DS}=20\text{V}$ , $I_D=8\text{A}$ , $V_{GS}=10\text{V}$	-	3.2	-	nC
$Q_{gd}$	Gate-Drain("Miller") Charge		-	3.1	-	nC
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD}= 20\text{V}$ , $R_L = 2.5\Omega$ $V_{GS}=10\text{V}$ , $R_{REN} = 3\Omega$	-	4	-	ns
$t_r$	Turn-on Rise Time		-	3	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	15	-	ns
$t_f$	Turn-off Fall Time		-	2	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_S$	Maximum Continuous Drain to Source Diode Forward Current	-	-	8	A	
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current	-	-	32	A	
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}$ , $I_S= 8\text{A}$	-	-	1.2	V

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

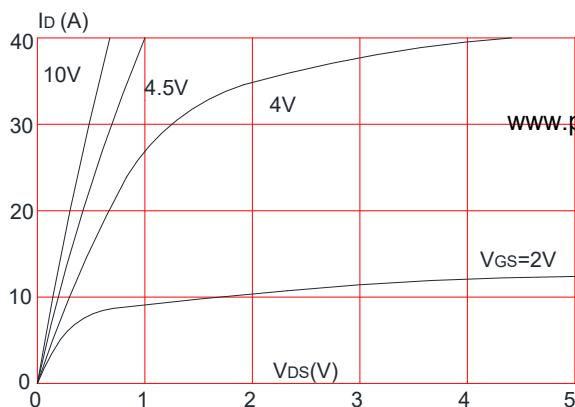
2. EAS condition :  $T_J=25^\circ\text{C}$ ,  $V_{DD}=20\text{V}$ ,  $V_G=10\text{V}$ ,  $L=0.5\text{mH}$ ,  $R_g=25\Omega$ ,  $I_{AS}=7.2\text{A}$

$T_J=25^\circ\text{C}$ ,  $V_{DD}=-20\text{V}$ ,  $V_G= -10\text{V}$ ,  $L=0.5\text{mH}$ ,  $R_g=25\Omega$ ,  $I_{AS}=-8.4\text{A}$

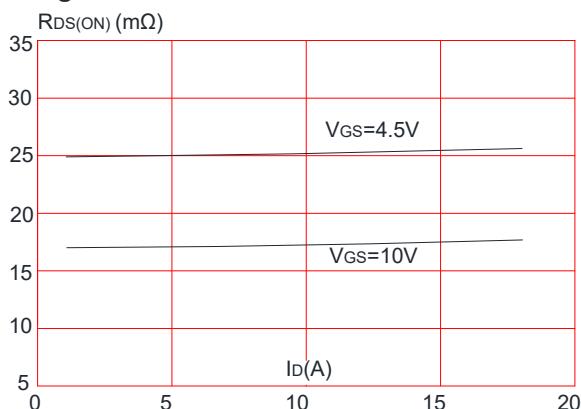
3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$ , Duty Cycle $\leq 2\%$

## Typical Performance Characteristics-N

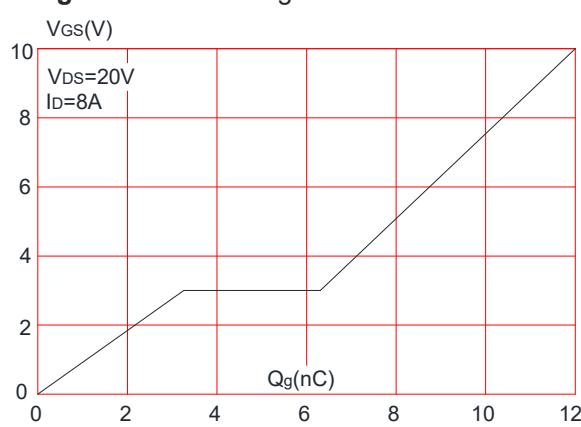
**Figure 1:** Output Characteristics



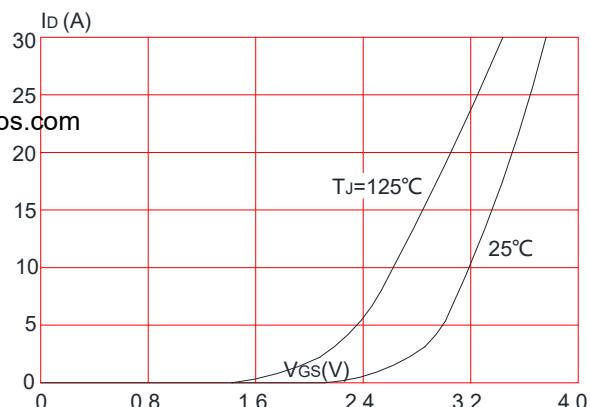
**Figure 3:** On-resistance vs. Drain Current



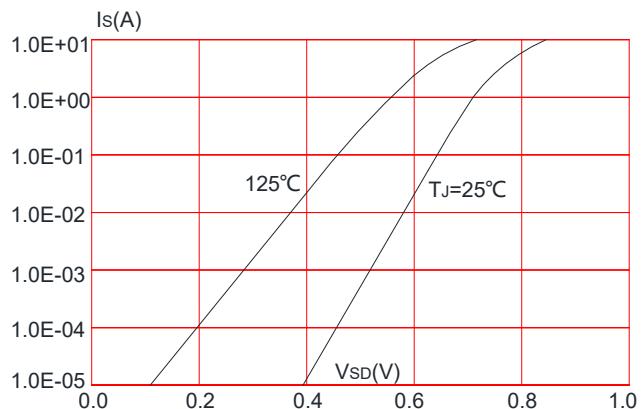
**Figure 5:** Gate Charge Characteristics



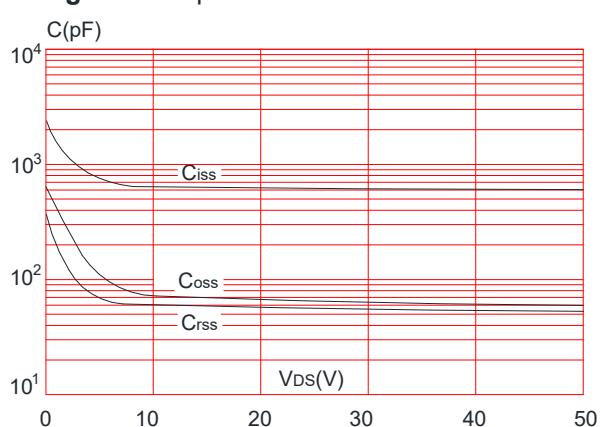
**Figure 2:** Typical Transfer Characteristics



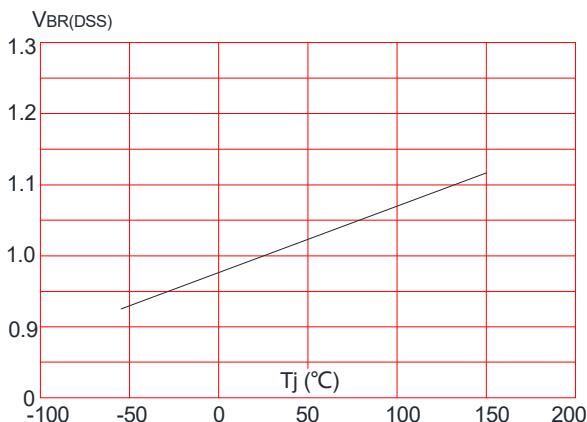
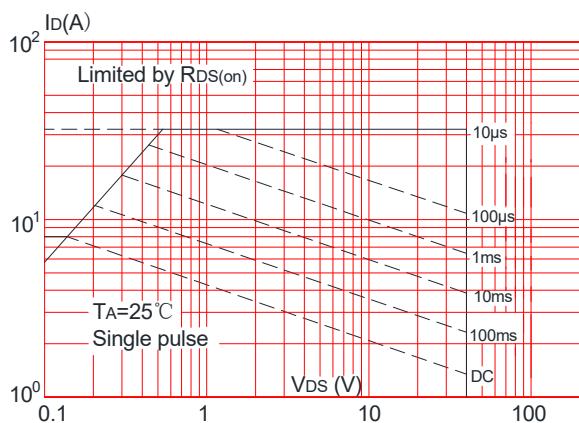
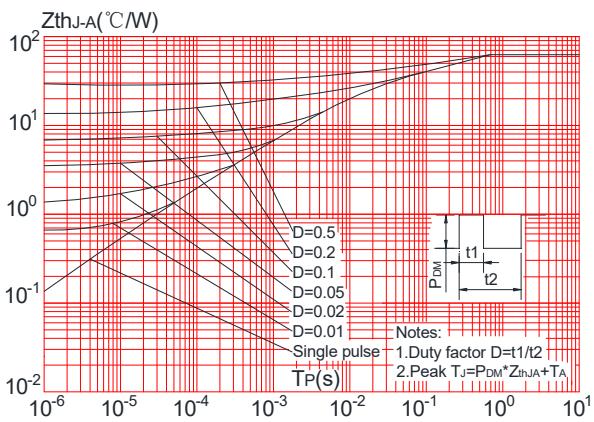
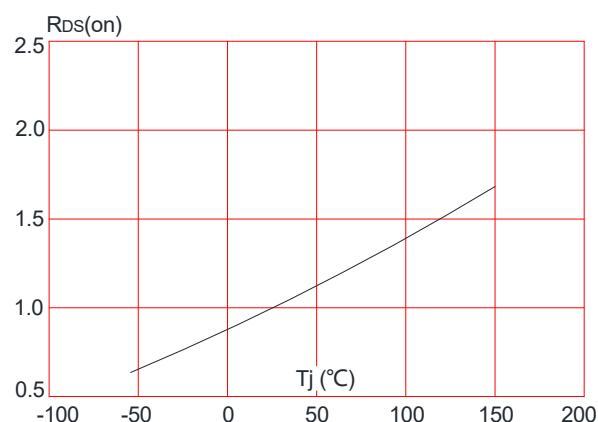
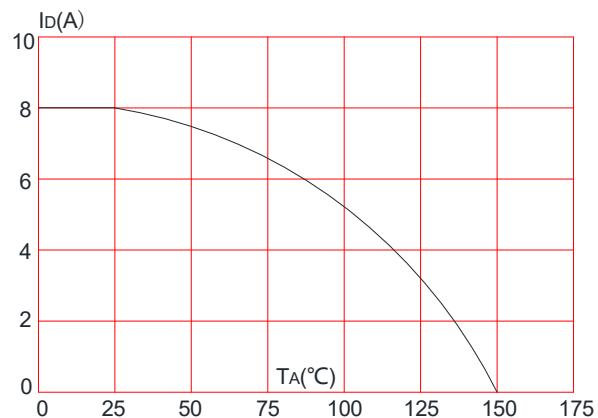
**Figure 4:** Body Diode Characteristics



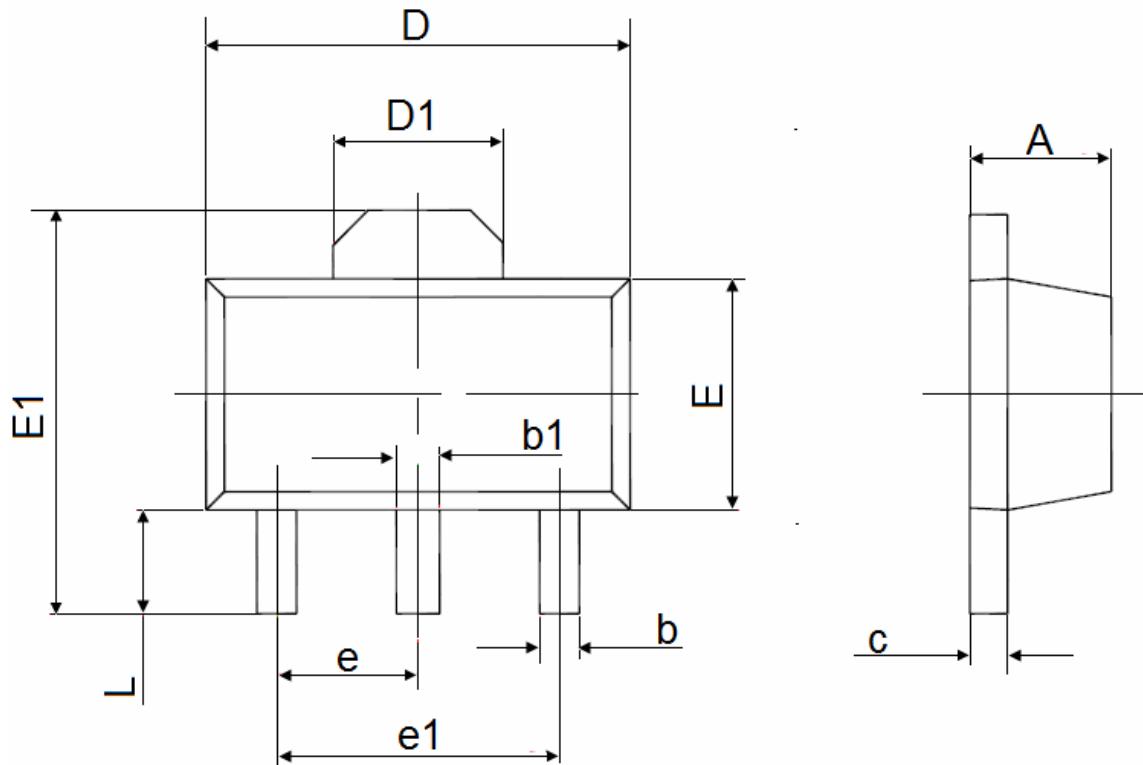
**Figure 6:** Capacitance Characteristics



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**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature**Figure 9:** Maximum Safe Operating Area**Figure 11:** Maximum Effective Transient Thermal Impedance, Junction-to-Ambient**Figure 8:** Normalized on Resistance vs. Junction Temperature**Figure 10:** Maximum Continuous Drain Current vs. Ambient Temperature

## SOT-89-3L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.400	1.600	0.055	0.063
b	0.320	0.520	0.013	0.020
b1	0.400	0.580	0.016	0.023
c	0.350	0.440	0.014	0.017
D	4.400	4.600	0.173	0.181
D1	1.550 REF.		0.061 REF.	
E	2.300	2.600	0.091	0.102
E1	3.940	4.250	0.155	0.167
e	1.500 TYP.		0.060 TYP.	
e1	3.000 TYP.		0.118 TYP.	
L	0.900	1.200	0.035	0.047